

What is claimed is:

1. An IC package structure comprising:

an IC package at least having a signal input terminal and a signal output terminal, and a plurality of grounding conductor plates being provided around its surrounding thereof;

a first conductor plate for covering over said IC package and having downwardly flexed edges at its both sides to form two lugs, wherein each of said lug has several screw fitting holes, and each of said grounding conductor plate is upwardly cambered to wrap said first conductor plate;

a second conductor plate having a similar shape to said first conductor plate, for covering said closely coupled first and grounding conductor plates, wherein both sides of said second conductor plate are also downwardly flexed to form two lugs, each lug is provided with several fitting holes; and

a press block configured to have an inner cavity to shade said IC package, said first and said second conductor plates, wherein several elastic press bars are installed in said inner cavity of said press block and located above said grounding conductor plates, corner screw fitting holes are provided around the surrounding of said press block so as to engage said press block, said second and said first conductor plates together with fixing screws by screwing into said screw fitting holes thereby completing assembly of said IC package.

2.The IC package structure as in claim 1, wherein number of said grounding conductor plate is one or more.

3.The IC package structure as in claim 1, wherein said press block has several inner slots for said elastic press bars to fit into and emerge downwardly to press said grounding conductor plates, said first and said second conductor plates beneath.

4.The IC package structure as in claim 1, wherein said grounding conductor plate is engaged by welding for enhancing tightness.